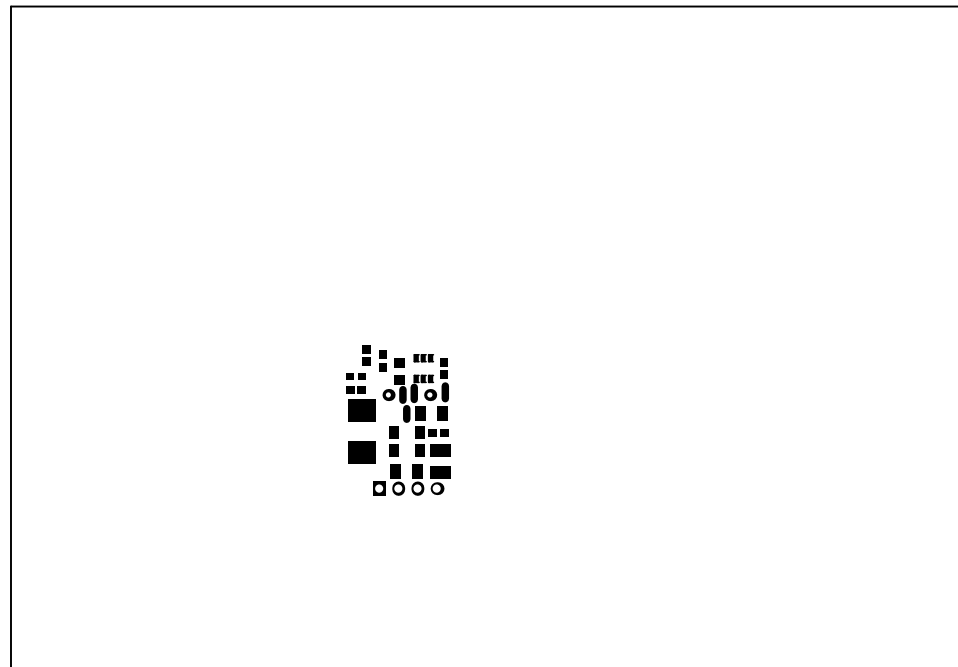
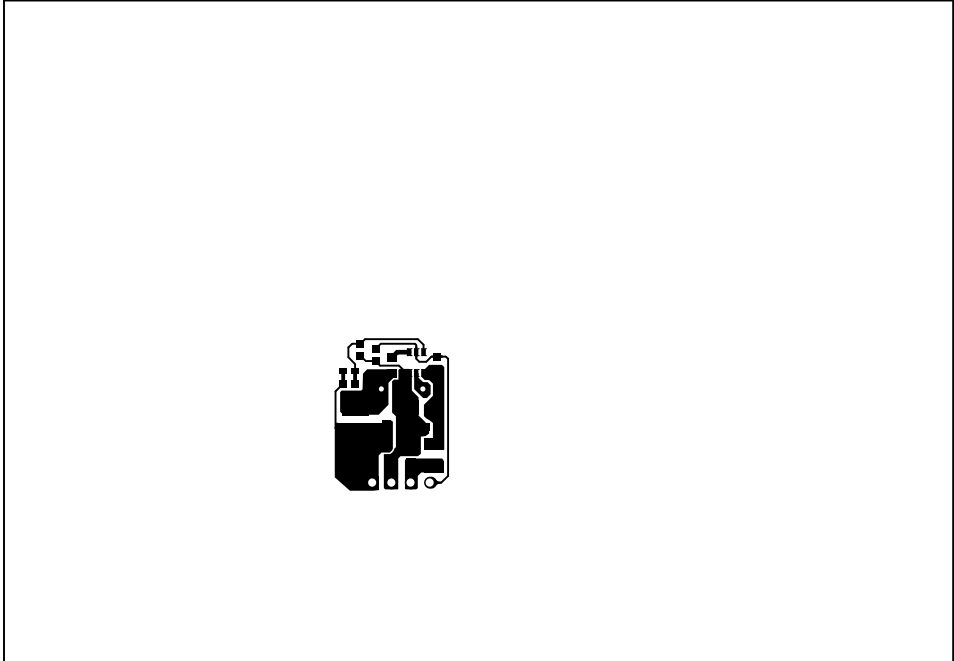


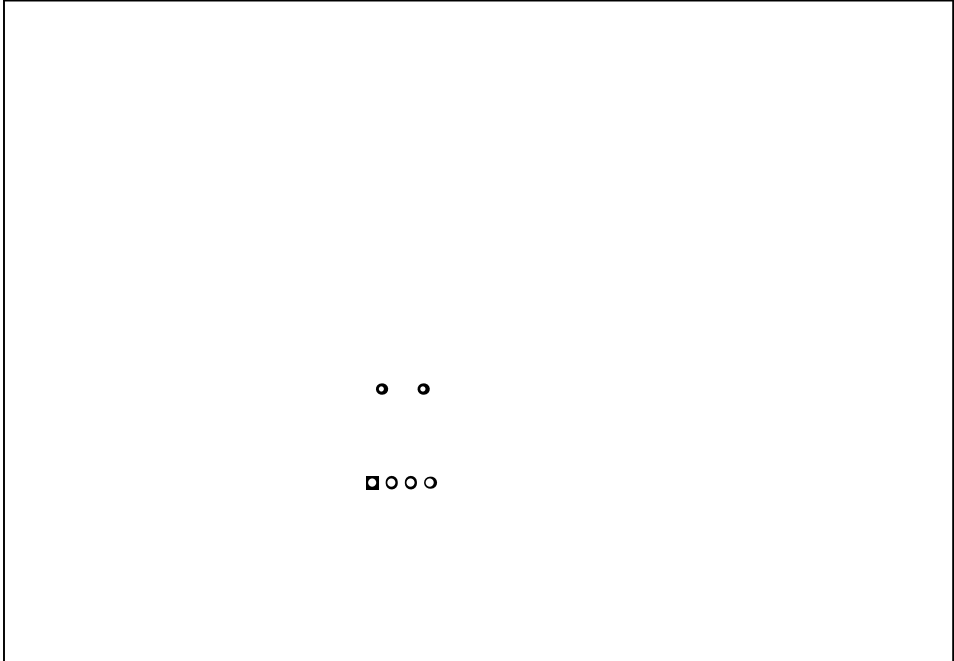
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01447	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01447		
PLOT NAME = Top Overlay	GENERATED : 7/3/2017 18:18:03	TEXAS INSTRUMENTS	



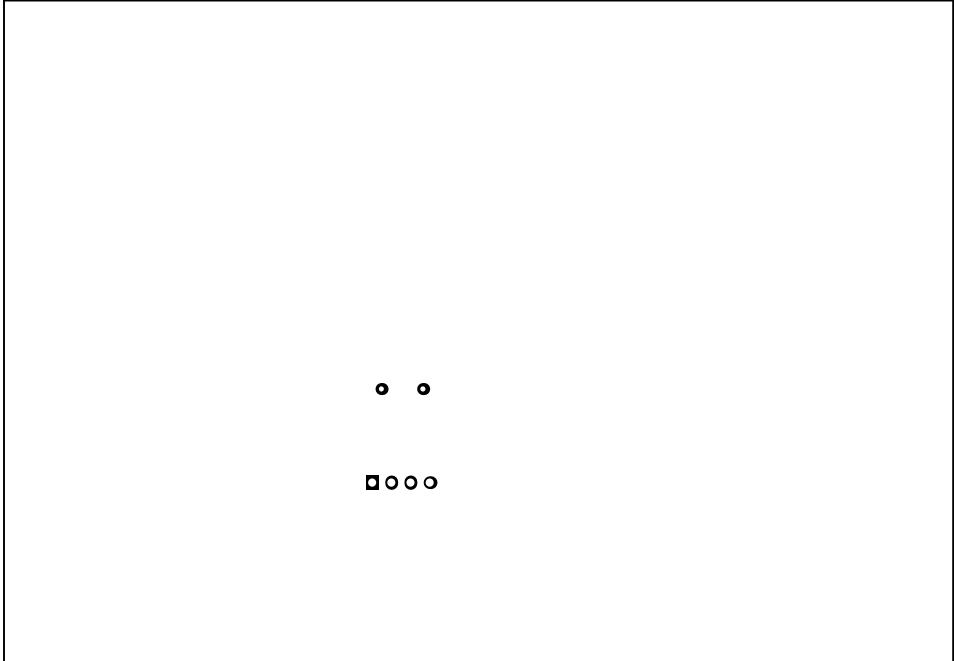
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01447	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01447		
PLOT NAME = Top Solder Mask	GENERATED : 7/3/2017 18:18:03	TEXAS INSTRUMENTS	



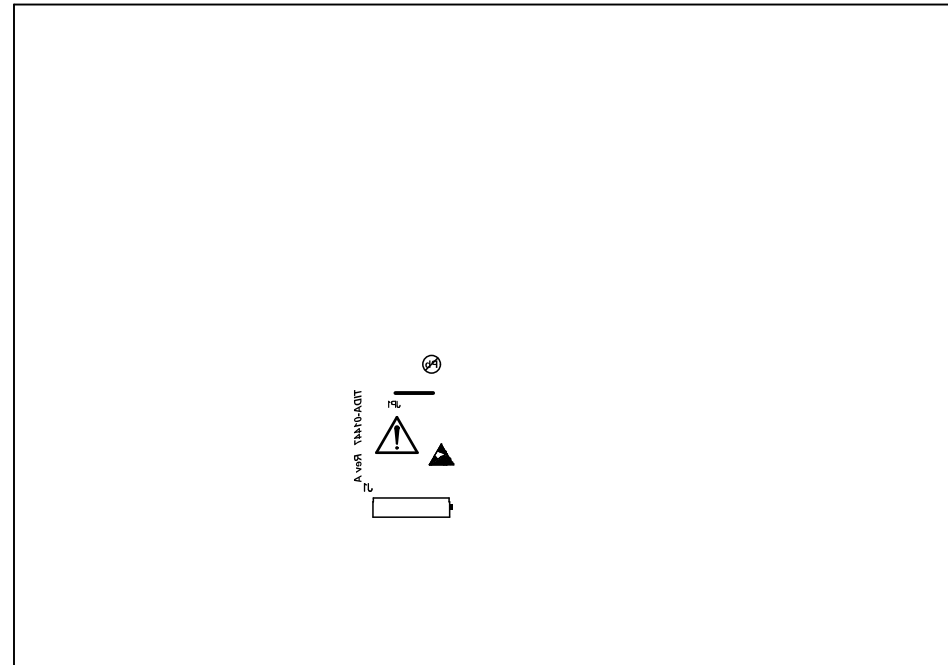
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01447	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01447		
PLOT NAME = Top Layer	GENERATED : 7/3/2017 18:18:04	TEXAS INSTRUMENTS	



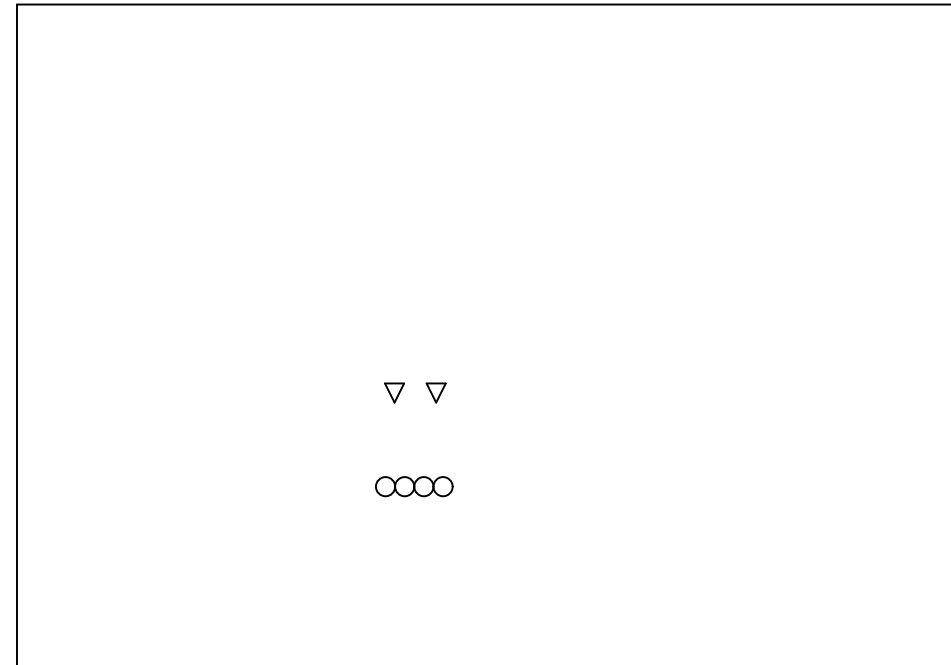
ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01447	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01447		
PLOT NAME = Bottom Layer	GENERATED : 7/3/2017 18:18:05	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01447	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Bottom Solder	TID #: TIDA-01447		
PLOT NAME = Bottom Solder Mask	GENERATED : 7/3/2017 18:18:05	TEXAS INSTRUMENTS	

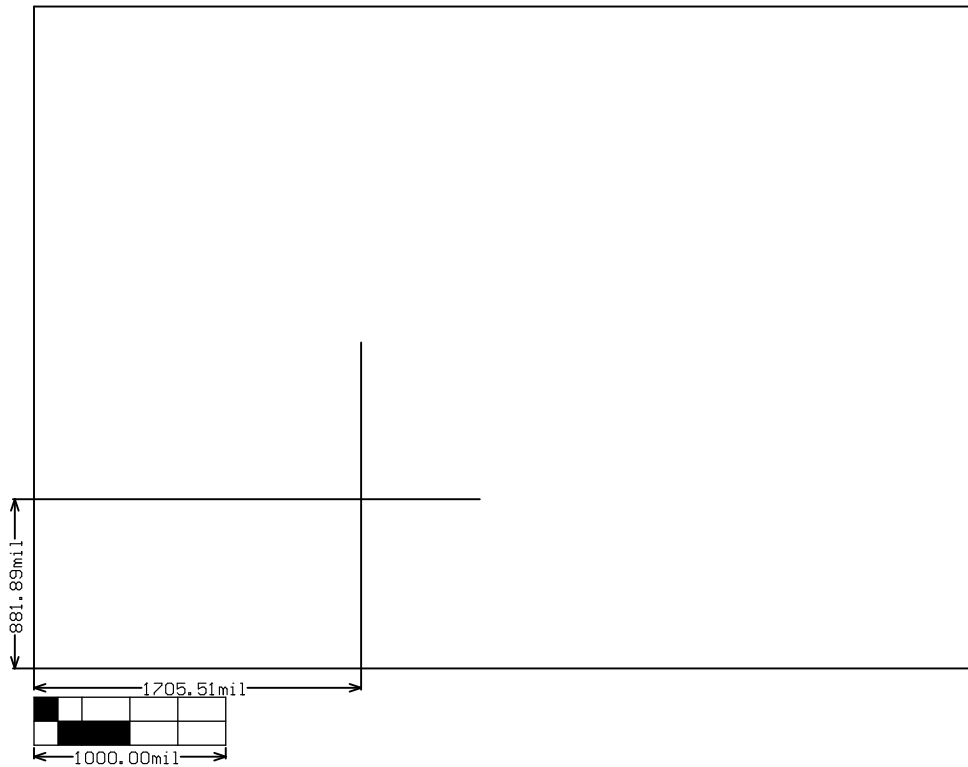


ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01447	REV: E1	SUN REV: Not In VersionControl
LAYER NAME =	TID #: TIDA-01447		
PLOT NAME = Bottom Overlay	GENERATED : 7/3/2017 18:18:06	TEXAS INSTRUMENTS	



Symbol	Quantity	Finished Hole Size	Plated	Hole Type
▽	2	27.56mil (0.700mm)	PTH	Round
○	4	43.31mil (1.100mm)	PTH	Round
	6 Total			

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01447	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = Drill Drawing	TID #: TIDA-01447		
PLOT NAME = Drill Drawing	GENERATED : 7/3/2017 18:18:07	TEXAS INSTRUMENTS	



ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: TIDA-01447	REV: E1	SUN REV: Not In VersionControl
LAYER NAME = M2 Board Dimensions	TID #: TIDA-01447		
PLOT NAME = Board Dimensions	GENERATED : 7/3/2017	18:18:07	TEXAS INSTRUMENTS

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